Zener Diode

### DZ4J120K0R

# **Panasonic**

# DZ4J120K0R

### Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

### ■ Features

- Excellent rising characteristics of zener current Iz
- · Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol:RJ
- Basic Part Number : Dual DZ2J120 (Parallel)

### ■ Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

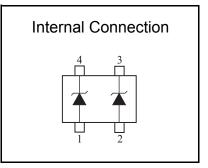
### ■ Absolute Maximum Ratings Ta = 25 °C

Symbol	Rating	Unit
IFRM	200	mA
PT	200	mW
ESD	±8	kV
Tj	150	°C
Topr	-40 to +85	°C
Tstg	-55 to +150	°C
	IFRM PT ESD Tj Topr	IFRM         200           PT         200           ESD         ±8           Tj         150           Topr         -40 to +85

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm) Solder in ( 0.8 mm x 0.8 mm)

# Unit: mm 2. 0 0. 3 0. 13 4 1. Anode-1 2. Anode-2 2. Anode-2 4. Cathode-1 Panasonic SMini4-F3-B

Panasonic	SMini4-F3-B
JEITA	SC-113BB
Code	_



### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	11.40		12.60	V
Zener operating resistance	RZ	IZ = 5  mA			30	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			80	Ω
Reverse current	IR	VR = 9 V			0.05	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5  mA		9.3		mV/°C

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. Absolute frequency of input and output is 5 MHz.
  - 3. \*1: The temperature must be controlled 25  $^{\circ}$ C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25  $^{\circ}$ C)
    - \*2: VZ guaranted 20 ms after current flow.
    - \*3: Tj = 25 °C to 150 °C

Established: 2009-12-11

Revised

: 2013-10-04

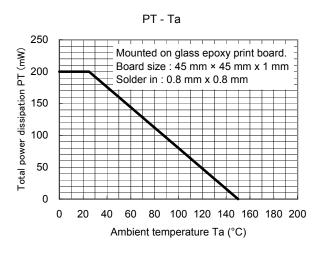
<sup>\*2:</sup> Test method:IEC61000\_4\_2(C = 150 pF,R = 330  $\Omega$ , Contact discharge:10 times)

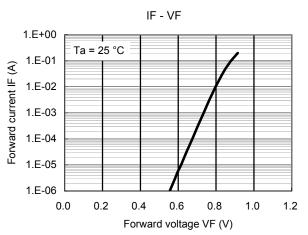
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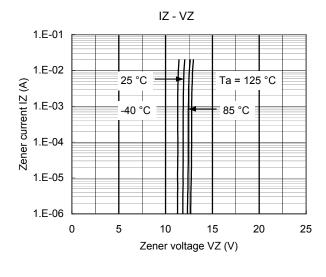
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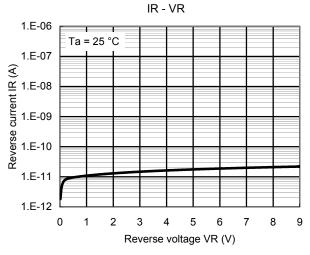
### DZ4J120K0R

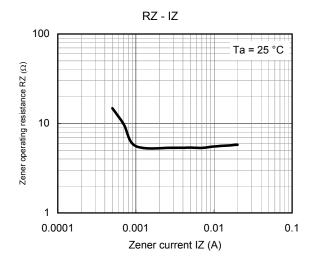
# Technical Data (reference)

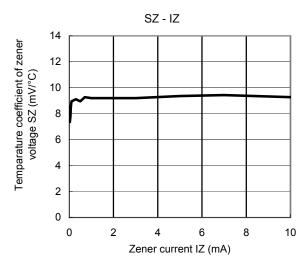












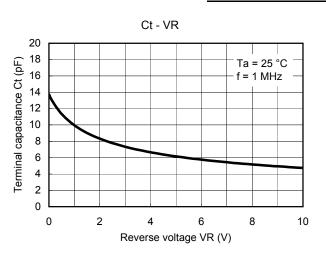
Established: 2009-12-11 Revised: 2013-10-04 Doc No. TT4-EA-12001 Revision. 3

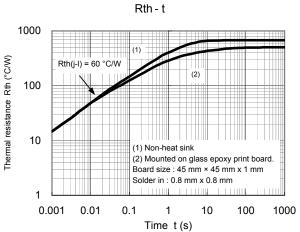
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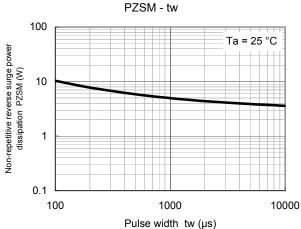
Zener Diode

### **DZ4J120K0R**

# Technical Data (reference)







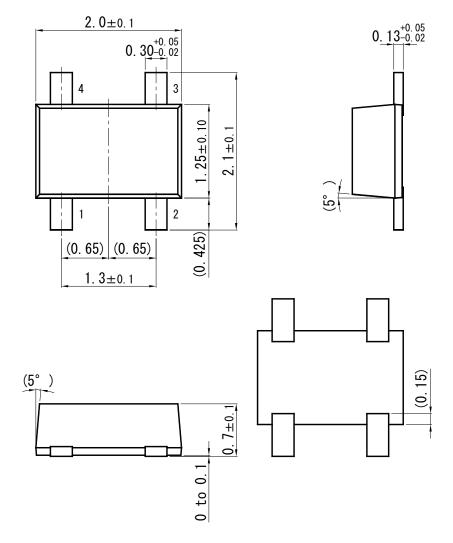
Established: 2009-12-11 Revised: 2013-10-04 Panasonic DZ

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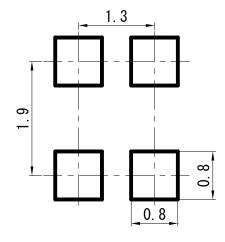
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# SMini4-F3-B

Unit: mm



### ■ Land Pattern (Reference) (Unit: mm)



Established: 2009-12-11 Revised: 2013-10-04

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